









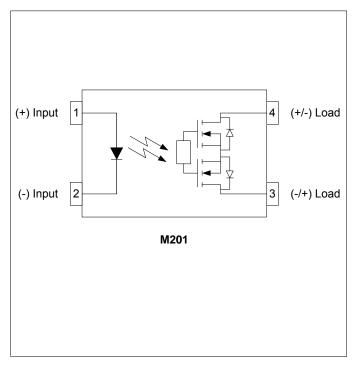
The M201 is a bi-directional, single-pole, single-throw, normally open multipurpose solid-state relay in a miniature 4-pin small outline package. With a high blocking voltage (600V) and low on-resistance, it is ideally suited to high voltage applications requiring higher load currents. The relay consists of an integrated circuit that drives two rugged source-to-source enhancement type DMOS transistors optically coupled to a light emitting diode. The output MOS transistors are protected with free-wheeling diodes that can handle up to 1.5A of inrush current

The M201 comes standard in a 4 pin SOP package.

Applications

- Reed Relay Replacement
- Security Systems
- Meter Reading Equipment
- **Data Acquisition**
- **Battery Monitoring**
- Multiplexers

Schematic Diagram



Features

- High Input-to-Output Isolation (1500V MIN)
- Low Input Control Current (2mA TYP)
- 140mA Maximum Continuous Load Current
- Low On Resistance (17Ω TYP)
- Ultra Miniature 4SOP Package
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL: File # E201932

VDF: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	55 to +125°C
Operating Temperature	40 to +85°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	5V
Input Power Dissipation	40mW
Total Power Dissipation	400mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature - IR Reflow (10sec)	260°C

Ordering Information

Part Number Description

M201 4 pin SOP, (100/Tube)

M201-TR 4 pin SOP, Tape and Reel (2000/Reel)

NOTE: Suffixes listed above are not included in marking on device for part number identification

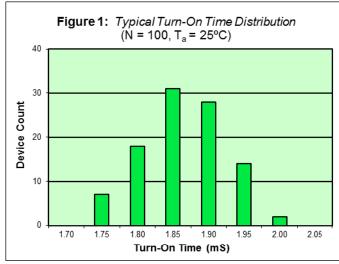


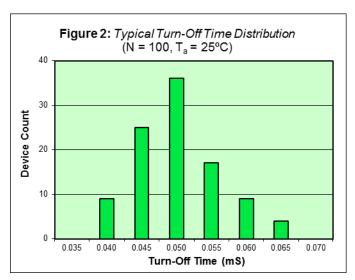
Electrical Characteristics, T_A = 25°C (unless otherwise specified)

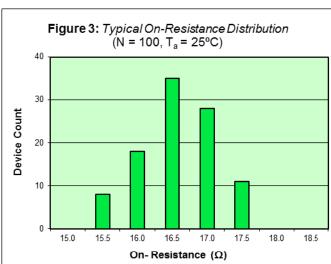
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions			
Input Specifications									
LED Forward Voltage	V _F	-	1.2	1.5	V	I _F = 10mA			
LED Reverse Voltage	BV _R	5	-	-	V	I _R = 10μA			
Input Reverse Current	I _R	-	-	10	μА	V _R = 5V			
Turn-On Current	I _F	-	2	5	mA	V _O = 20V, I _O = 140mA (within 10mS)			
Turn-Off Current	I _{F(OFF)}	-	0.5	-	mA	I _O = 140mA			
Output Specifications									
Blocking Voltage	V _B	600	-	-	V	Ι _Ο =1μΑ			
Continuous Load Current	Io	-	-	140	mA	I _F =5mA			
On Resistance	R _{on}	-	17	20	Ω	I _F =5mA, I _O =140mA			
Leakage Current	I _{Oleak}	-	0.2	1	μА	I _F =0mA, V _O =600V			
Output Capacitance	C _{OUT}	-	20	-	pF	V _O =25V, f=1.0MHz			
Offset Voltage	V _{OFFSET}	-	-	0.2	mV	I _F =5mA			
Coupled Specifications									
Turn-On Time	T _{ON}	-	2	5	mS	I _F =5mA, I _O =140mA			
Turn-Off Time	T _{OFF}	-	0.05	1	mS	I _F =0mA, I _O =140mA			
Coupled Capacitance	C _{COUPLED}	-	3	-	pF				
Contact Transient Ratio	-	2,000	7,000	0	V/μS	dV = 50V			
Isolation Specifications									
Isolation Voltage	V _{ISO}	1500	-	-	V _{RMS}	RH ≤ 50%, t=1min			
Input-Output Resistance	R _{I-O}	-	10 ¹²	-	Ω	V _{I-O} = 500V _{DC}			

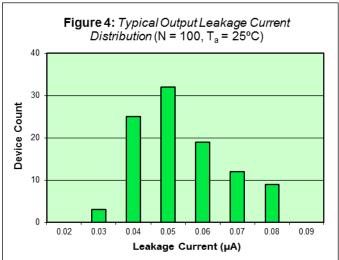


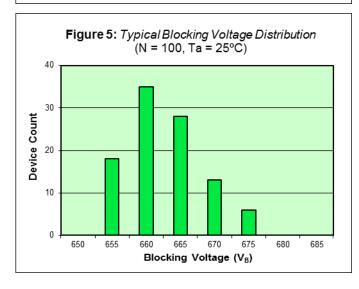
M201 Performance & Characteristics Plots, TA = 25°C (unless otherwise specified)

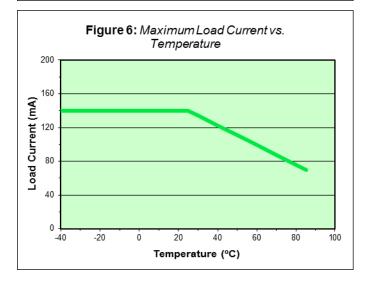










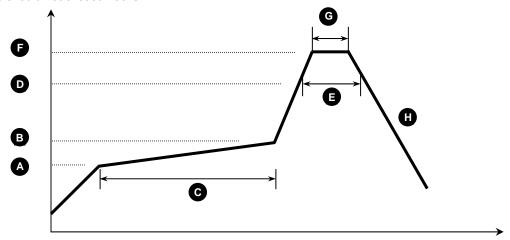




M201 Solder Reflow Temperature Profile Recommendations

(1) Infrared Reflow:

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:



Process Step	Description	Parameter	
Α	Preheat Start Temperature (°C)	150°C	
В	Preheat Finish Temperature (°C)	180°C	
С	Preheat Time (s)	90 - 120s	
D	Melting Temperature (°C)	230°C	
E	Time above Melting Temperature (s)	30s	
F	Peak Temperature, at Terminal (°C)	260°C	
G	Dwell Time at Peak Temperature (s)	10s	
Н	Cool-down (°C/s)	<6°C/s	

(2) Wave Solder:

Maximum Temperature: 260°C (at terminal)

Maximum Time: 10s

Pre-heating: 100 - 150°C (30 - 90s)

Single Occurrence

(3) Hand Solder:

Maximum Temperature: 350°C (at tip of soldering iron)

Maximum Time:

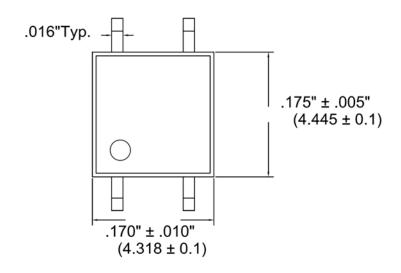
Single Occurrence

3s

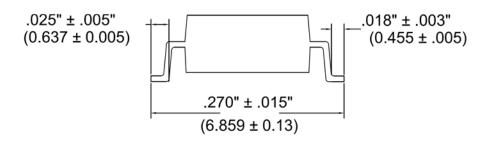
M201 Package Dimensions

4 PIN SOP Package

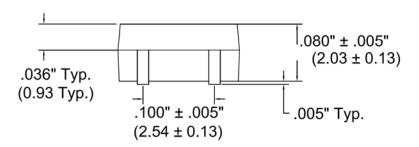
Note: All dimensions in inches with millimeters [mm] in parenthesis ()



TOP VIEW



END VIEW



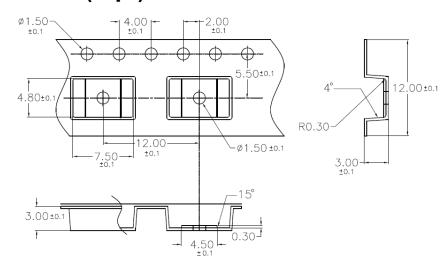
SIDE VIEW

Note: All dimensions in millimeters [mm]

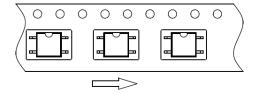
M201 Packaging Specifications

Tape & Reel Specifications (T&R)

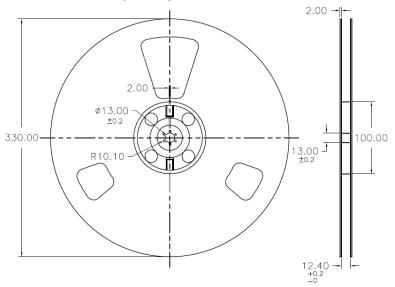
Outline and Dimension (Tape)



Parts Orientation and Tape Direction



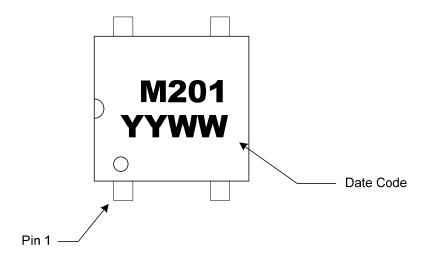
Outline and Dimensions (Reel)



Packaging: 2,000 pcs / reel



M201 Package Marking



M201 Package Weights

Device	Single Unit	Full Tube (100pcs)	Full Pouch (10 tubes)	Full Reel (2000pcs)
M201	0.10	23	240	-
M201-TR	0.10	-	-	500

Note: All weights above are in GRAMS, and include packaging materials where applicable

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